Single Chip 3-Axis Magnetic Sensor QMC7983



The QMC7983 is a three-axis magnetic sensor, which integrates magnetic sensors and signal condition ASIC into one silicon chip. This wafer level chip scale package (WLCSP) is targeted for applications such as e-compass, map rotation, gaming and personal navigation in mobile and wearable devices.

The QMC7983 is based on our state-of-the-art, high resolution, magneto-resistive technology. Along with the custom-designed 16-bit ADC ASIC, it offers the advantages of low noise, high accuracy, low power consumption, offset cancellation and temperature compensations. QMC7983 enables 1° to 2° compass heading accuracy. The I²C serial bus allows for easy interface.

The QMC7983 is in a 1.2x1.2x0.55mm³ surface mount 8-pin WLCSP package.

FEATURES

- 3-Axis Magneto-Resistive Sensors in a 1.2x1.2x0.55 mm³ WLCSP, Guaranteed to Operate Over an Extended Temperature Range of -40 °C to +85 °C.
- 16 Bit ADC With Low Noise AMR Sensors Achieves 2 milli-Gauss Field Resolution
- Wide Magnetic Field Range (±20 Gauss)
- Temperature Compensated Data Output and Temperature Output
- ▶ I²C Interface with Standard and Fast Modes.
- Built-In Self-Test
- Wide Range Operation Voltage (2.4V To 3.6V) and Low Power Consumption (75μA)
- Lead Free Package Construction
- Software And Algorithm Support Available

BENEFIT

- Small Size for Highly Integrated Products. Signals Have Been Digitized And Calibrated.
- Enables 1° To 2° Degree Compass Heading Accuracy , Allows for Pedestrian Navigation and LBS Applications
- Maximizes Sensor's Full Dynamic Range and Resolution
- Automatically Maintains Sensor's Sensitivity Under Wide Operating Temperature Range
- High-Speed Interfaces for Fast Data Communications. Maximum 200Hz Data Output Rate
- Enables Low-Cost Functionality Test After Assembly in Production
- Compatible with Battery Powered Applications
- RoHS Compliance
- Compassing Heading, Hard Iron, Soft Iron, and Auto Calibration Libraries Available



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1 INTERNAL SCHEMATIC DIAGRAM

1.1 Internal Schematic Diagram

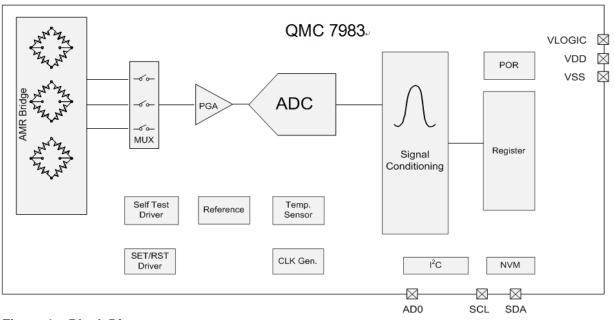


Figure 1. Block Diagram

Table 1. Block Function

Block	
Block	Function
AMR Bridge	3-axis magnetic sensor
MUX	Multiplexer for sensor channels
PGA	Programmable gain amplifier for sensor signals
ADC	Analog-to-Digital converter
Signal Conditioning	Digital blocks for magnetic signal calibration and compensations
l ² C	Interface logic data I/O
NVM	Non-volatile memory
Self-Test Driver	Internal driver to generate self-test stimulus
SET/RST Driver	Internal driver to initialize magnetic sensor
Reference	Voltage/current reference for internal biasing
Clock Gen.	Internal oscillator for internal operation
POR	Power on reset
Temperature Sensor	Temperature sensor for internal sensitivity /offset compensation

2 SPECIFICATIONS AND I/O CHARACTERISTICS

2.1 **Product Specifications**

Table 2. Specifications (Tested and specified at 25°C except stated otherwise.)

Parameter	Condition	S	Min	Тур	Max	Unit
Supply Voltage	VDD	-	2.4	- 71-	3.6	V
I/O Voltage	VLOGIC		1.65		3.6	V
Standby Current		ent on VDD and		3		μΑ
	Low/Hig h Power	ODR = 10Hz		75/100		μA
Continuous Mode Current	Mode	ODR = 50Hz		150/250		μA
Ourient	(OSR=6 4 or 512)	ODR = 100Hz		250/450		μA
	,	ODR = 200Hz		450/850		μA
Peak Current in Active State	Peak Curre VLOGIC D Measurem			2.6		mA
Sensor Field Range	Full Scale	X,Y Z	-20 -10		+20 +10	Gauss
Dynamic Output Field Range	Programm	able X,Y Z	±	2, ±8, ±12, ±	20	Gauss
	Field Rang	$e = \pm 2G$		10000		LSB/G
Sensitivity [1]	Field Rang			2500		LSB/G
Sensitivity	Field Rang	je = ±12G		1666		LSB/G
	Field Rang	je = ±20G		1000		LSB/G
Linearity	Field Rang	je = ±2G (X-Y) (Z Axis)		0.2 1.0		%FS
(Best fit linear curve)	Field Rang	$ge = \pm 8G (X-Y)$ (Z Axis)		0.6		%FS
Hysteresis	All Ranges			0.3		%FS
Cross Axis Sensitivity		= 1 Gauss, ±2 Gauss		0.1		%/G
Offset				±10		mG
Sensitivity Tempco	Ta = -40°C	C~85°C		±0.05		%/°C
Temperature Sensor Sensitivity	Ta = -40°C	C ~85°C		100		LSB/°C
Digital Resolution	Change wi	th Gain	0.1		1.0	mGauss
Field Resolution		leviation 100 2G (X-Y) (Z)		2		mGauss
Output Data Rate	Programm 10Hz/50Hz	able. z/100Hz/200Hz	10		200	Samples /sec
Self-Test	Register 0	9H by 0x32		1200 2280		LSB
X-Y-Z Orthogonality	Sensitivity	Directions		90±1		Degree
Operating Temperature			-40		85	°C
ESD	HB Model		2000		1	V

Note [1]: Sensitivity is calibrated at zero field, it is slightly decreased at high fields.

2.2 Absolute Maximum Ratings

Parameter	MIN.	MAX.	Units		
VDD	-0.3	3.6	V		
VLOGIC	-0.3	3.6	V		
Storage Temperature	-40	125	°C		
Exposed to Magnetic Field (all directions)		50000	Gauss		
Reflow Classification	MSL 1, 260 °C F	Peak Temperature			

Table 3. Absolute Maximum Ratings (Tested at 25°C except stated otherwise.)

2.3 I/O Characteristics

Table 4. I/O Characteristics

Parameter	Symbol	Pin	Condition	Min.	TYP.	Max.	Unit
Voltage Input	V _{IH} 1	SDA, SCL		0.7*VLO		VLOGIC	V
High Level 1				GIC		+0.3	
Voltage Input	V _{IL} 1	SDA, SCL		-0.3		0.3*VLO	V
Low Level 1						GIC	
Voltage Output	V _{OH}	INT	Output Current	0.8*VLO			V
High Level			≥-100uA	GIC			
Voltage Output	V _{OL}	INT, SDA	Output Current			0.2*VLO	V
Low Level			≤100uA(INT)			GIC	
			Output Current				
			≤1mA (SDA)				

3 PACKAGE PIN CONFIGURATIONS

3.1 Package 3-D View

Arrow indicates direction of magnetic field that generates a positive output reading in normal measurement configuration. < OMC7983 >

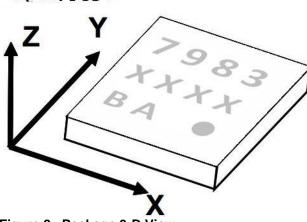


Figure 2. Package 3-D View

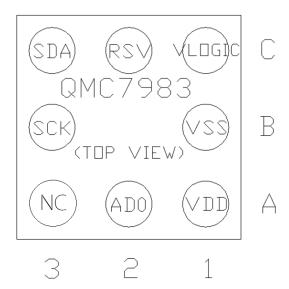


Figure 3. Package Top View

Table	5.	Pin	Configurations
Table	J.		ooningurationa

PIN	PIN	I/O	Power	TYPE	Function			
No.	NAME		Supply					
A1	VDD	-	POWER	Power	Supply voltage			
A2	AD0	Ι	VDD	CMOS(Analog)	I ² C address			
A3	NC							
B1	VSS	-	POWER	Power	Ground			
B3	SCK	Ι	VLOGIC	CMOS	I ² C clock			
C1	VLOGIC	-	VLOGIC	Power	I/O supply voltage			
C2	RSV							
C3	SDA	I/O	VLOGIC	CMOS	I ² C data			

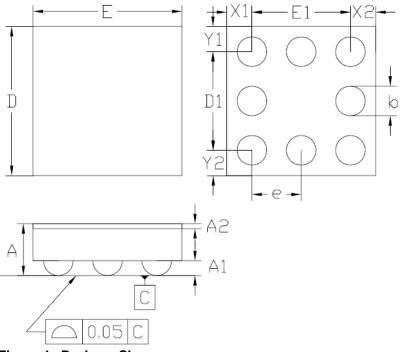
3.2 Package Outlines

3.2.1 Package Type

WLCSP

3.2.2 Package Size:

1.2mm (Length)*1.2mm (Width)*0.55mm (Height)



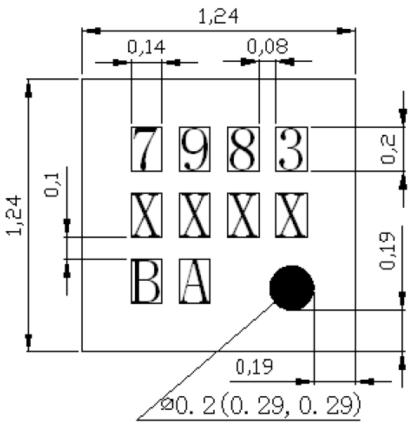
(COMMON DIMENSIONS				
(UNITS	OF MEASU	RE=MILLIN	(ETER)		
SYMBOL	MIN	NOM	MAX		
A	0.530	0.550	0.570		
A1	0.110	0.140	0.170		
A2	0.020	0.035	0.050		
D	1.170	1.200	1.230		
E	1.170	1.200	1.230		
D1		0.800BSC			
E1		0.800BSC			
е		0.400BSC			
b	0.210	0.240	0.270		
X1	0.200REF				
X2	0.200REF				
y1	0.200REF				
y2		0.200REF			

Figure 4. Package Size

3.2.3

Marking: Tracking code:

7983: fixed code by customer order fixed code XXXX BA:





4 EXTERNAL CONNECTION

4.1 Recommended external connection

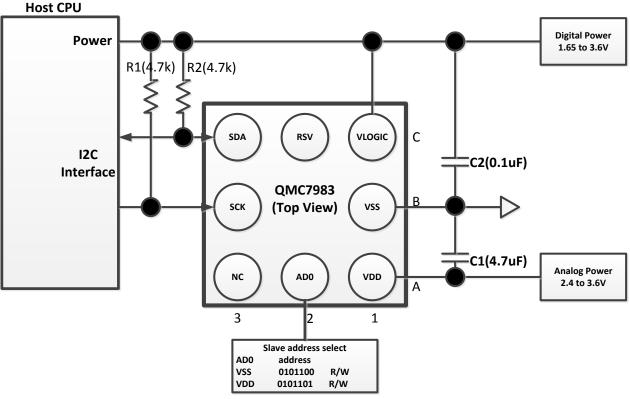
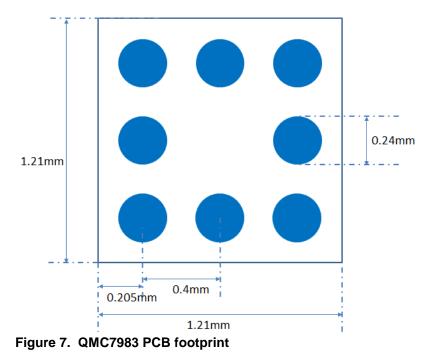


Figure 6. External Connection

4.3 Mounting Considerations

The following is the recommend printed circuit board (PCB) footprint for the QMC7983. Due to the fine pitch of the pads, the footprint should be properly centered in the PCB.



4.4 Layout Considerations

Besides keeping all components that may contain ferrous materials (nickel, etc.) away from the sensor on both sides of the PCB, it is also recommended that there is no conducting copper line under/near the sensor in any of the PCB layers.

4.4.1 Solder Paste

A 4 mil stencil and 100% paste coverage is recommended for the electrical contact pads.

4.4.2 Reflow Assembly

This device is classified as MSL 1 with 260°C peak reflow temperature. Reference IPC/JEDEC standard J-STD-033 for additional information.

No special reflow profile is required for QMC7983, which is compatible with lead eutectic and lead-free solder paste reflow profiles. QST recommends adopting solder paste manufacturer's guidelines. Hand soldering is not recommended.

4.4.3 External Capacitors

The external capacitors C1 should be ceramic type with low ESR characteristics. The exact ESR value is not critical, but values less than 200 milli-ohms are recommended. Reservoir capacitor C1 is nominally 4.7 μ F in capacitance. Low ESR characteristics may not be in many small SMT ceramic capacitors (0402), so be prepared to up-size the capacitors(0201) to gain low ESR characteristics.

5 BASIC DEVICE OPERATION

5.1 Anisotropic Magneto-Resistive Sensors

The QMC7983 magneto-resistive sensor circuit consists of tri-axial sensors and application specific support circuits to measure magnetic fields. With a DC power supply is applied to the sensor two terminals, the sensor converts any incident magnetic field in the sensitive axis directions to a differential voltage output.

The device has an offset cancellation function to eliminate sensor and ASIC offsets. It also applies a self-aligned magnetic field to restore magnetic state before each measurement to ensure high accuracy. Because of these features, the QMC7983 doesn't need to calibrate every time in most of application situations. It may need to be calibrated once in a new system or a system changes a new battery.

5.2 **Power Management**

There are two power supply pins to the device. VDD provides power for all the internal analog and digital functional blocks. VLOGIC provides power for digital I/O and logic.

The device should turn-on both power pins in order to operate properly. When the device is powered on, all registers are reset by POR, then the device transits to the standby mode and waits for further commends.

Table 6 provides references for four power states. Transitions between power state 2 and power state 3 are prohibited, due to leakage current concerns.

Power State	VDD	VLOGIC	Power State description
1	0V	0V	Device Off, No Power Consumption
2	0V	1.65V~3.6V	Device Off, Unpredictable Leakage Current on VLOGIC due to Floating Node.
3	2.4V~3.6V	0	Device Off, Same Current as Standby Mode
4	2.4V~3.6V	1.65V~3.6V	Device On, Normal Operation Mode, Enters Standby Mode after POR

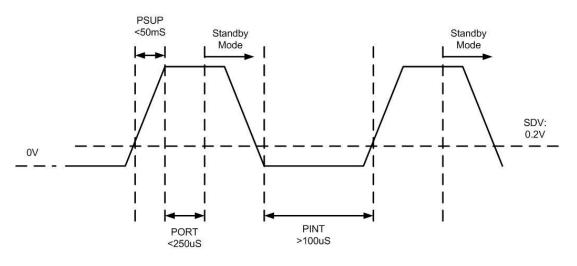
Table 6: Power States

5.3 Power On/Off Time

After the device is powered on, some time periods are required for the device fully functional. The external power supply requires a time period for voltage to ramp up (PSUP), it is typically 50 milli-second. However it isn't controlled by the device. The Power –On –Reset time period (PORT) includes time to reset all the logics, load values in NVM to proper registers, enter the standby mode and get ready for analogy measurements. The power on/off time related to the device is in Table 7.

Table 7. Time Required for Power	On/Off
----------------------------------	--------

Parameter	Symbol	Condition	Min.	Тур.	Max.	Unit
POR	PORT	Time Period After VDD and			250	uS
Completion		VLOGIC at Operating Voltage				
Time		to Ready for I ² C Commend				
		and Analogy Measurement.				
Power off	SDV	Voltage that Device Considers			0.2	V
Voltage		to be Power Down.				
Power on	PINT	Time Period Required for	100			uS
Interval		Voltage Lower Than SDV to				
		Enable Next POR				



Power On/Off Timing

Figure 8. Power On/Off Timing

5.4 Communication Bus Interface I²C and Its Addresses

This device will be connected to a serial interface bus as a slave device under the control of a master device, such as the processor. Control of this device is carried out via I²C.

This device is compliant with I²C -Bus Specification, document number: 9398 393 40011. As an I²C compatible device, this device has a 7-bit serial address and supports I²C protocols. This device supports standard and fast speed modes, 100kHz and 400kHz, respectively. External pull-up resistors are required to support all these modes.

There are two I^2C addresses selected by connecting pin A2 (AD0) to VSS or VDD. The first six MSB are hardware configured to "010110" and the LSB can be configured by AD0.

AD0	I ² C Slave Address(HEX)	I ² C Slave Address(BIN)
Connect to VSS	2CH	0101100
Connect to VDD	2DH	0101101

Table 8. I²C Address Options

If more l^2C address options are required, please contact factory.

5.5 Internal Clock

The device has an internal clock for internal digital logic functions and timing management. This clock is not available to external usage.

5.6 Temperature Compensation

Temperature compensation of the measured magnetic data is enabled by default at the factory. Temperature measured by the built-in temperature sensor will be used to compensate the magnetic sensor's sensitivity changes due to temperatures. The compensated magnetic sensor data is placed in the Output Data Registers automatically.

5.7 Temperature Output

QMC7983 has a built-in temperature sensor, it can provide temperature reading for other applications. The output is placed in Temperature Output Registers (07H and 08H). The temperature is calibrated for its sensitivity.

6 MODES OF OPERATION

6.1 Modes Transition

The device has three different operational modes, controlled by register (09H), mode bits. The main purpose of these modes is for power management and self-assessment. The modes can be transited from one to another, as shown below, through I²C commends of changing mode bits. The default mode is Standby.

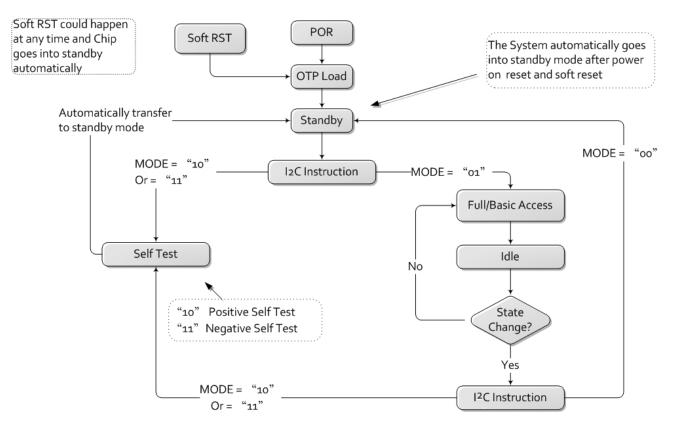


Figure 9. Modes Transition

6.2 Description of Modes

6.2.1 Continuous-Measurement Mode

During the continuous-measurement mode (mode bits= 01), the magnetic sensor continuously makes measurements and places measured data in data output registers. The field range (or sensitivity) and data output rate registers are also located in the control register (09H), they should be set up properly for your applications in the continuous-measurement mode.

For example, if the application requires output date rate 50Hz, the ODR bit in control register (09H) should be 01. If the field range is +/-12 Gauss, the RNG =10.

The over sample rate is optional for you to use. The default is OSR=00, if your application has enough resolution and need low power consumption, you may reduce OSR to a lower number, such as OSR=10 (128) or OSR =11 (64).

In the continuous-measurement mode, the magnetic sensor data are automatically compensated for offset and temperature effects. The gains are calibrated in the factory.

6.2.1.1 Normal Read Sequence

Complete magnetometer data read-out can be done as follow steps.

- ♦ poll DRDY in Register 06H
- ♦ Read DRDY in Register 06H (if polling, it's unnecessary)

DRDY: Data ready ("1") or Not ("0").

DOR: Any data has been missed ("1") or not ("0")

- ♦ Read measured data, if any of the six data register is accessed, DRDY and DOR turn to "0".
- Data protection, if any of the six data register is accessed, data protection starts. During Data protection period, data register cannot be updated until the last bits 05H (ZOUT [15:8]) have been read.
- DRDY bit should not be set if any data read is during operation. It may result in nest setting.
- x/y/z registers are updated at the edge when x LSB is read, and status register (0x06) depends on whether z MSB is read.

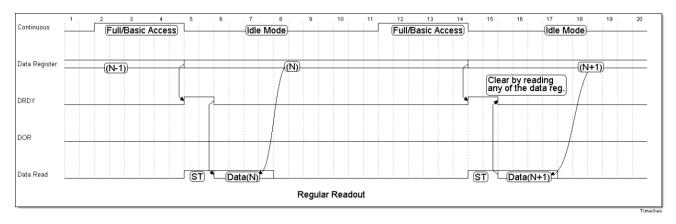


Figure 10. Normal Read Sequence

6.2.1.2 Data Read Sequence Occurs at Measurement

During measurement, it's possible to read data register which keep the previous measured data. Therefore, no DRDY bit will be set if data reading occurs at the middle of measurement.

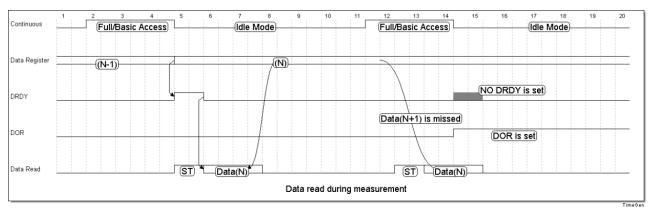


Figure 11 Data Read Sequence at Measurement

6.2.1.3 Data Not Read

If Nth data is skipped, the current data will be flushed by next coming data. In this case, DRDY bit keeps high until data is read. DOR bit is set to "1" which indicates a set of measurement data has been lost. DOR bit turns to "0" once 06H is accessed in next data read operation

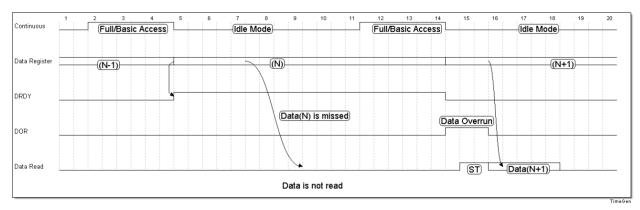


Figure 12. Sequence When Data Not Read

6.2.1.4 Data Locks Until Next Measurement Ends

Data lock is activated once any of the data register is accessed. If 05H (data unlock) is not accessed until next measurements ends, current data blocks next data to update data register. In this case, DOR bit is also set to "1" until 06H is accessed in next data read.

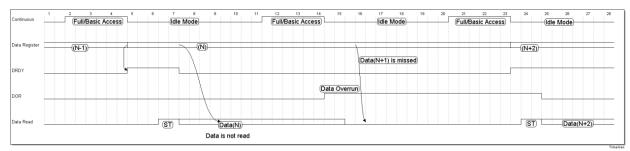


Figure 13. Sequence When Data Locks

6.2.2 Standby Mode

Standby mode is the default magnetometer state upon POR and soft reset. Only few function blocks are activated in this mode which keeps power consumption as low as possible. In this state, register values are hold on by a lower power LDO, I2C interface is active and all register reads and writes are allowed. There is no magnetometer measurement in the Standby state. Internal clocking is halted, this means charge pump dedicated to SET/RESET is also deactivated.

6.2.3 Self-Test Mode

Self-test mode is used to check if the sensor is working normally. By sinking or sourcing the current upon test coil, a magnetic field is generated to change the chip's output.

7 Application Examples

7.1 Continuous Mode Setup Example

Write Register 0BH by 0x0F (Define Set/Reset ratio, execute 1 time Set/Reset in every 65 times measurement)
 Write Register 09H by 0x3D (Define OSR = 512, Full Scale Range = 20 Gauss, ODR = 200Hz, set continuous measurement mode)

7.2 Measurement Example

- ♦ Check status register 06H[0] ,"1" means ready.
- ♦ Read data register 00H ~ 05H.

7.3 Self-test Example

- ♦ Write Register 09H by 0x32 (Full Scale Range = 20 Gauss, not recommend to change)
- ♦ Waiting 3 millisecond until measurement ends
- ♦ Read data Register 00H ~ 05H
- ♦ Check data if within specification

7.4 Standby Example

♦ Write Register 09H by 0x00

7.5 Soft Reset Example

♦ Write Register 0AH by 0x80

8 I²C COMMUNICATION PROTOCOL

8.1 I²C Timings

Below table and graph describe the I²C communication protocol times

Table 9. I ² C Timings						
Parameter	Symbol	Condition	Min.	Тур.	Max.	Unit
SCL Clock	fscl		0		400	kHz
SCL Low Period	tlow		1			μS
SCL High Period	t _{high}		1			μS
SDA Setup Time	t _{sudat}		0.1			μS
SDA Hold Time	t _{hddat}		0		0.9	μS
Start Hold Time	t _{hdsta}		0.6			μS
Start Setup Time	t _{susta}		0.6			μS
Stop Setup Time	t _{susto}		0.6			μS
New Transmission Time	t _{buf}		1.3			μS
Rise Time	tr					μS
Fall Time	t _f					μS

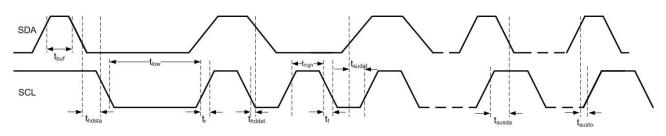


Figure 14. I²C Timing Diagram

I²C Timing Diagram

8.2 I²C R/W Operation

8.2.1 Abbreviation

Table 10. Abbreviation

SACK	Acknowledged by slave
MACK	Acknowledged by master
NACK	Not acknowledged by master
RW	Read/Write

8.2.2 Start/Stop/Ack

START: Data transmission begins with a high to transition on SDA while SCL is held high. Once I²C transmission starts, the bus is considered busy.

STOP: STOP condition is a low to high transition on SDA line while SCL is held high.

ACK: Each byte of data transferred must be acknowledged. The transmitter must release the SDA line during the acknowledge pulse while the receiver mush then pull the SDA line low so that it remains stable low during the high period of the acknowledge clock cycle.

NACK: If the receiver doesn't pull down the SDA line during the high period of the acknowledge clock cycle, it's recognized as NACK by the transmitter.

8.2.3 I²C Write

I²C write sequence begins with start condition generated by master followed by 7 bits slave address and a write bit (R/W=0). The slave sends an acknowledge bit (ACK=0) and releases the bus. The master sends the one byte register address. The slave again acknowledges the transmission and waits for 8 bits data which shall be written to the specified register address. After the slave acknowledges the data byte, the master generates a stop signal and terminates the writing protocol.

Table 11. I²C Write

S	Slav	e Ac	ddre	ess		R			Re	gis		Ad	dre	SS						Da						
Ξí						W	Š				(0x	09)				Š				(0x	01)				Ş	ST
AR	0 1 0) 1	1	0	0	0	õ	0	0	0	0	1	0	0	1	õ	0	0	0	0	0	0	0	1	õ	<u>o</u>
Ĥ																										P

8.2.4 I^2 C Read

 I^2C write sequence consists of a one-byte I^2C write phase followed by the I^2C read phase. A start condition must be generated between two phase. The I^2C write phase addresses the slave and sends the register address to be read. After slave acknowledges the transmission, the master generates again a start condition and sends the slave address together with a read bit (R/W=1). Then master releases the bus and waits for the data bytes to be read out from slave. After each data byte the master has to generate an acknowledge bit (ACK = 0) to enable further data transfer. A NACK from the master stops the data being transferred from the slave. The slave releases the bus so that the master can generate a STOP condition and terminate the transmission.

The register address is automatically incremented and more than one byte can be sequentially read out. Once a new data read transmission starts, the start address will be set to the register address specified in the current I²C write command.

Tub				<u> </u>																								
S		SI	ave	e Ac	ddre	ess		R W	Ş		Re			Ad 09)		SS		SA										
START	0	0	0	1	1	0	0	0	SACK	0	0	0	0	1	0	0	1	ACK										
လု		SI	ave	e Ac	ddre	ess		R W	S				Da (0y	ata 00)				<				Da (0x						
START	0	0	0	1	1	0	0	1	SACK	0	0	0	0	0	0	0	0	MACK	0	0	0	0	0	0	0	1		
M,					Data 0x02				Ň									Ň				Da (0x					Ķ	R
MACK	0	0	0	0	0	0	1	0	MACK	····								MACK	0	0	0	0	0	1	1	1	NACK	STOP

Table 12. I²C Read

8.2.5 I²C Pointer Roll-over

QMC7983 has an embedded I²C pointer roll-over function which can improve the data transmission efficiency. The I²C data pointer will automatically roll between 00H ~ 06H if I²C read begins at any position among 00H~06H. This function is enabled by set 0AH[6] = 01H.

9 **REGISTERS**

9.1 Register Map

The table below provides a list of the 8-bit registers embedded in the device and their respective function and addresses

Table 13. Register Map

Addr.	7	6	5	4	3	2	1	0	Access					
00H	Data Ou	tput X LSE	3 Register	XOUT[7	:0]				Read only					
01H	Data Ou	tput X MS	B Register	r XOUT[1	15:8]				Read only					
02H	Data Ou	tput Y LSE	3 Register	YOUT[7:0)]				Read only					
03H	Data Ou	tput Y MSI	B Registei	r YOUT[15	5:8]				Read only					
04H	Data Ou	tput Z LSE	8 Register	ZOUT[7:0)]				Read only					
05H	Data Ou	Data Output Z MSB Register ZOUT[15:8]												
06H						DOR	OVL	DRD	Read only					
								Υ						
07H	TOUT[7:	0]							Read only					
08H	TOUT[1	5:8]							Read only					
09H	OSR[1:0]	RNG[1:0)]	ODR[1:	:0]	MODE	[1:0]	Read/Write					
0AH	SOFT_								R/W, Read					
	RST								only on					
									blanks					
0BH	SET/RE	SET/RESET Period FBR [7:0]												
0CH		OTP_	Read only											
								RDY						
0DH	CHIPID<	<7:0>							Read only					

9.2 Register Definition

9.2.1 Output Data Register

Registers 00H ~ 05H store the measurement data from each axis magnetic sensor in continuous-measurement or self-test modes. In the continuous measurement mode, the output data is refreshed periodically based on the data update rate ODR setup in control registers 1. The data stays the same, regardless of reading status through I²C, until new data replaces them. Each axis has 16 bit data width in 2's complement, i.e., MSB of 01H/03H/05H indicates the sign of each axis. The output data of each channel saturates at -32768 and 32767.

Table 14.	Output	Data	Register
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		J						
Addr.	7	6	5	4	3	2	1	0
00H	Data Out	tput X LSI	B Register	XOUT[7]	:0]			
01H	Data Out	tput X MS	B Register	· XOUT[1	5:8]			
02H	Data Out	tput Y LSI	B Register	YOUT[7:	:0]			
03H	Data Out	tput Y MS	B Register	· YOUT[1	5:8]			
04H	Data Out	tput Z LSE	B Register	ZOUT[7:	0]			
05H	Data Out	tput Z MS	B Register	ZOUT[15	5:8]			

9.2.2 Status Register

There are two status registers located in address 06H and 0CH.

Register 06H has three bits indicating for status flags, the rest are reserved for factory use. The status registers are read only bits.

Table 15. Status Register 1

Addr.	7	6	5	4	3	2	1	0
06H						DOR	OVL	DRDY

Data Ready Register (DRDY), it is set when all three axis data is ready, and loaded to the output data registers in the continuous measurement mode or in the self-test mode. It is reset to "0" by reading any data register (00H~05H) through I²C commends

DRDY: "0": no new data, "1": new data is ready

Overflow flag (OVL) is set to "1" if any data of three axis magnetic sensor channels is out of range. The output data of each axis saturates at -32768 and 32767, if any of the axis exceeds this range, OVL flag is set to "1". This flag is reset to "0" if next measurement goes back to the range of (-32768, 32767), otherwise, it keeps as "1".

OVL: "0": normal, "1": data overflow

Data Skip (DOR) bit is set to "1" if all the channels of output data registers are skipped in reading in the continuous-measurement mode. It is reset to "0" by reading any data register (00H~05H) through I²C

DOR: "0": normal, "1": data skipped for reading

9.2.3 Temperature Data Registers

Registers 07H-08H store temperature sensor output data. 16 bits temperature sensor output is in 2's complement. Temperature sensor gain is factory-calibrated, but its offset has not been compensated, only relative temperature value is accurate. The temperature coefficient is about 100 LSB/ $^{\circ}$ C

Table 17. Temperature Sensor Output

Addr.	7	6	5	4	3	2	1	0
07H	TOUT[7:	0]						
08H	TOUT[15	5:8]						

9.2.4 Control Registers

Two 8-bits registers are used to control the device configurations.

Control register 1 is located in address 09H, it sets the operational modes (MODE). output data update rate (ODR), magnetic field measurement range or sensitivity of the sensors (RNG) and over sampling rate (OSR). Control register 2 is located in address 0AH. It controls soft reset (SOFT_RST).

Two bits of MODE registers can transfer mode of operations in the device, the three modes are Standby, Continuous measurements and self-test. The default mode after Power-on-Reset (POR) is standby. There is no any restriction in the transferring among the three modes.

Output data rate is controlled by ODR registers. Four data update frequencies can be selected: 10Hz, 50Hz, 100Hz and 200Hz. For most of compassing applications, we recommend 10 Hz for low power consumption. For gaming, the high update rate such as 100Hz or 200Hz can be used.

Field ranges of the magnetic sensor can be selected through the register RNG. The full scale field range is determined by the application environments. For magnetic clear environment, low field range such as +/- 2gauss can be used. The field range goes hand in hand with the sensitivity of the magnetic sensor. The lowest field range has the highest sensitivity, therefore, higher resolution. Four magnetic field ranges can be selected, 2Gauss, 8 Gauss, 12 Gauss and 20 Gauss.

Over sample Rate (OSR) registers are used to control bandwidth of an internal digital filter. Larger OSR value

leads to smaller filter bandwidth, less in-band noise and higher power consumption. It could be used to reach a good balance between noise and power. Four over sample ratio can be selected, 64, 128, 256 or 512.

Table 18. Control Register 1

Addr	7	6	5	4	3	2	1	0
09H	OSF	OSR[1:0]		[1:0]	ODF	R[1:0]	MOE	DE[1:0]
	_							-
Reg.	Definitio	on	00		01		10	11
Mode	Mode Co	Mode Control		Standby		ious	Self-	Reserve
							Test	
ODR	Output D	ata Rate	10Hz		50Hz		100Hz	200Hz
RNG	Full Scal	е	2G		8G		12G	20G
OSR	Over	Sample	512		256		128	64
	Ratio							

SOFT_RST: "0": Normal "1": Soft reset, restore default value of all registers.

Table 19. Control Register 2

Addr.	7	6	5	4	3	2	1	0
0AH	SOFT_R							
	SI							

9.2.5 SET/RESET Period Register

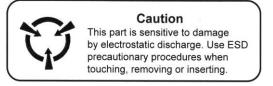
SET/RESET Period is controlled by FBR [7:0], it is recommended that the register 0BH is written by 0xFF, not change to any other value.

Table 20. SET/RESET Period Register

Addr.	7	6	5	4	3	2	1	0
0BH	SET/RESE	T Period FBI	R [7:0]					

ORDERING INFORMATION

Ordering Number	Temperature Range	Package	Packaging
QMC7983-TR	-40°C ~ 85°C	WLCSP	Tape and Reel: 5k pieces/reel



CAUTION: ESDS CAT. 1B

FIND OUT MORE

For more information on QST's Magnetic Sensors contact us at 86-21-69517300.

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U.S. Patents 4,441,072, 4,533,872, 4,569,742, 4,681,812, 4,847,584 and 6,529,114 apply to the technology described.

China Patents 201210563667.3, 201210563956.3, 201210563952.5, 201210563687.0, 201310403912.9, 201410027189.3, 201410027240.0, 201410027085.2 and 201410085278.3 apply to the technology described.



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